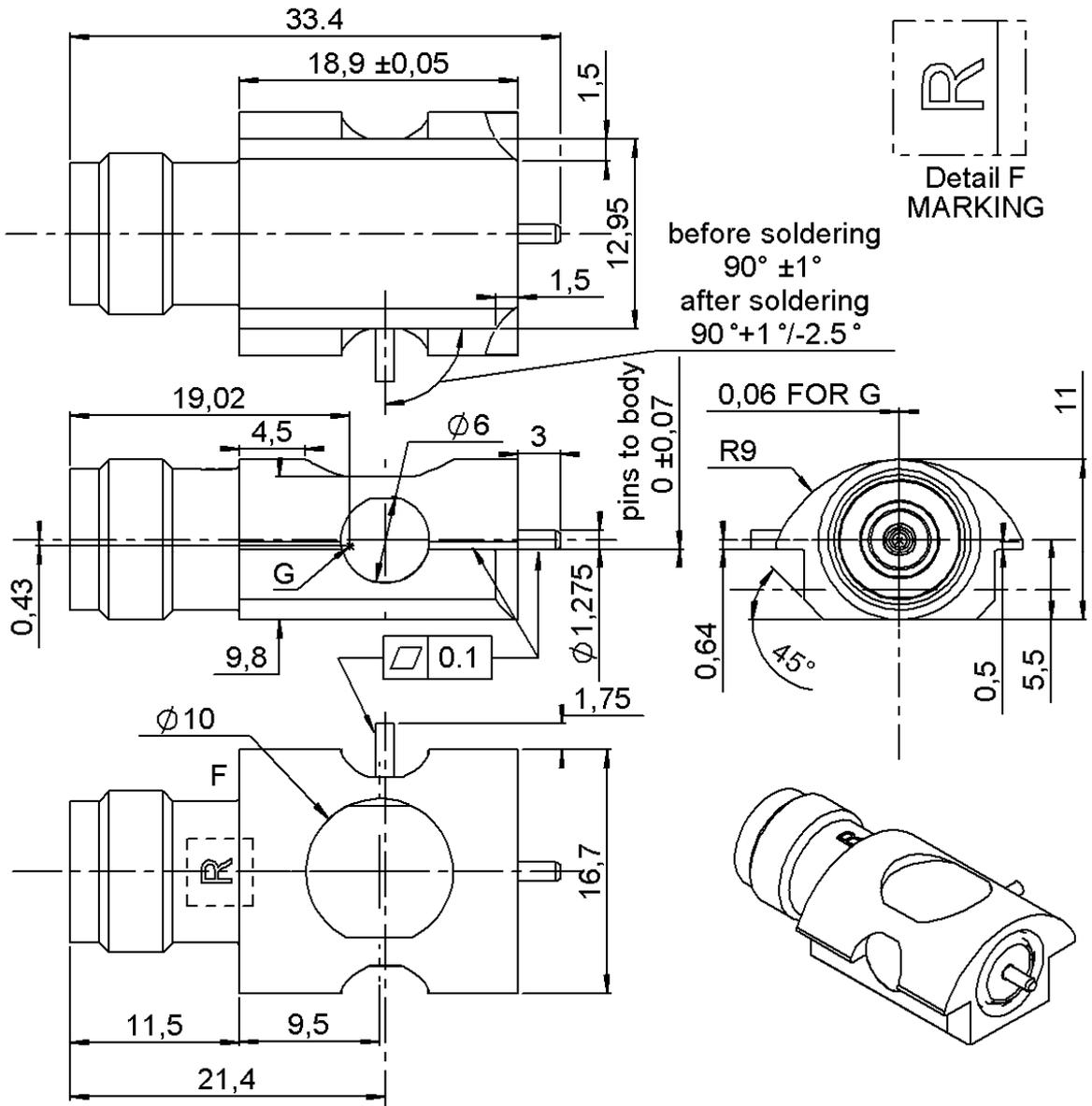


**TNC SWITCH-EDGE CARD-SMT LEFT TYPE**

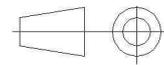
**R143.422.947**

**PACKAGING IN REEL 110**

Series : TNC



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
BODY	BRASS	NPGR
CENTER CONTACT	BERYLLIUM COPPER	NPGR
OUTER CONTACT	BRASS	NPGR
INSULATOR	PEEK	
GASKET	-	
OTHERS PARTS	BRASS	NPGR
-	-	-
-	-	-

Issue : 0823 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



**TNC SWITCH-EDGE CARD-SMT LEFT TYPE**

**R143.422.947**

**PACKAGING IN REEL 110**

Series : TNC

**PACKAGING**

**SPECIFICATION**

Standard	Unit	Other
<b>110</b>	<b>'W' option</b>	<b>Contact us</b>

**1301-RNT 408 4010 UEN rev C**

**ELECTRICAL CHARACTERISTICS**

**ENVIRONMENTAL**

Impedance	<b>50</b>	$\Omega$
Frequency	<b>DC-3</b>	GHz
VSWR	<b>1.1 + 0,1000</b>	x F(GHz) Maxi
Isolation at DC to 1 Ghz	<b>-47</b>	DB Typical
Isolation at 1 to 2 Ghz	<b>-43</b>	DB Typical
Isolation at 2 to 3 Ghz	<b>-40</b>	DB Typical
Insertion loss DC to 1 Ghz	<b>0.1</b>	$\sqrt{F}$ (GHz) dB Maxi
Insertion loss 1 to 2 Ghz	<b>0.15</b>	dB Maxi
Insertion loss 2 to 3 Ghz	<b>0.2</b>	dB Maxi
RF leakage	<b>NA</b>	- F(GHz)) dB Maxi
Voltage rating	<b>300</b>	Veff Maxi
Dielectric withstanding voltage	<b>500</b>	Veff mini
Insulation resistance	<b>5000</b>	M $\Omega$ mini
Power withstanding	<b>80</b>	W at 0.9 Ghz
	<b>50</b>	W at 1.9 Ghz

Operating temperature	<b>-40/+85</b>	$^{\circ}$ C
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

**OTHERS CHARACTERISTICS**

Assembly instruction

Others :  
Action Mating Force :  
20 N max  
15 N min

(1) Do not apply force on the center contac before Mounting the switch on PCB

**MECHANICAL CHARACTERISTICS**

Center contact retention		
Axial force – Mating end	<b>NA</b>	N mini
Axial force – Opposite end	<b>NA</b>	N mini
Torque	<b>NA</b>	N.cm mini
Axial force side pin	<b>(1)</b>	
Recommended torque		
Mating	<b>22</b>	N.cm
Panel nut	<b>NA</b>	N.cm
Mating life	<b>100</b>	Cycles mini
Weight	<b>20,9800</b>	g

Issue : 0823 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



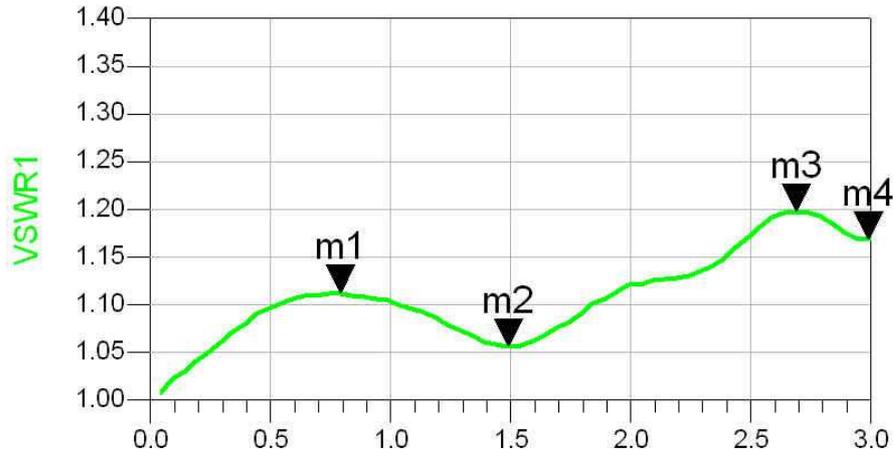
**TNC SWITCH-EDGE CARD-SMT LEFT TYPE**

**R143.422.947**

**PACKAGING IN REEL 110**

Series : TNC

VSWR direct line

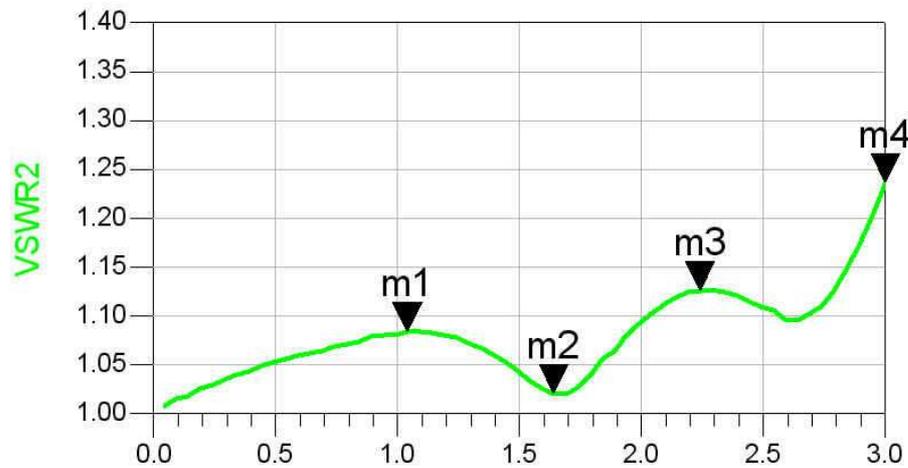


m1
freq=790.0MHz
VSWR1=1.112
m3
freq=2.690GHz
VSWR1=1.197

freq, GHz

m2
freq=1.490GHz
VSWR1=1.056
m4
freq=2.990GHz
VSWR1=1.169

VSWR switched line



m1
freq=1.040GHz
VSWR2=1.084
m3
freq=2.240GHz
VSWR2=1.126

freq, GHz

m2
freq=1.640GHz
VSWR2=1.021
m4
freq=3.000GHz
VSWR2=1.236

Issue : 0823 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



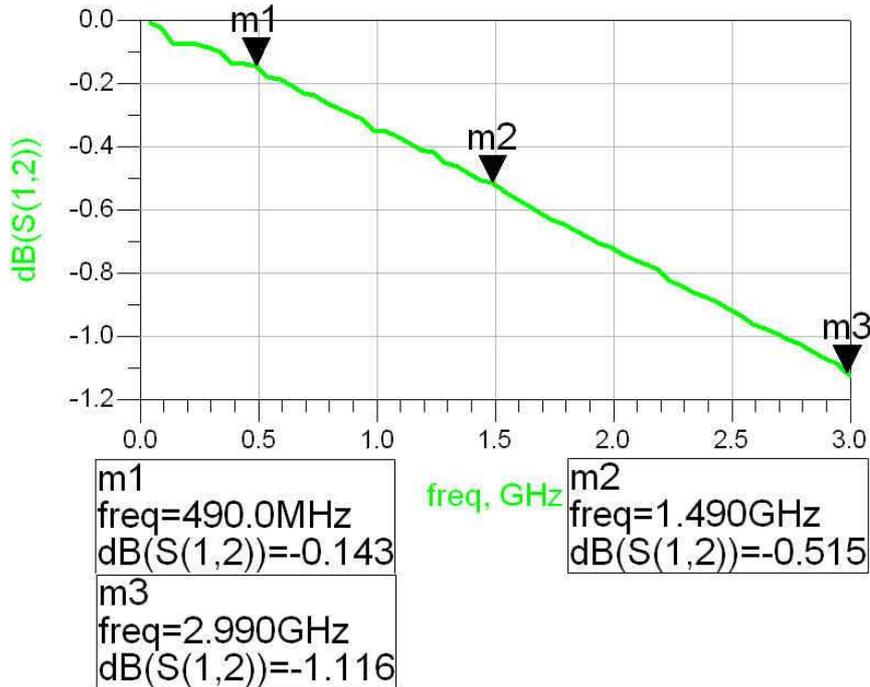
TNC SWITCH-EDGE CARD-SMT LEFT TYPE

**R143.422.947**

PACKAGING IN REEL 110

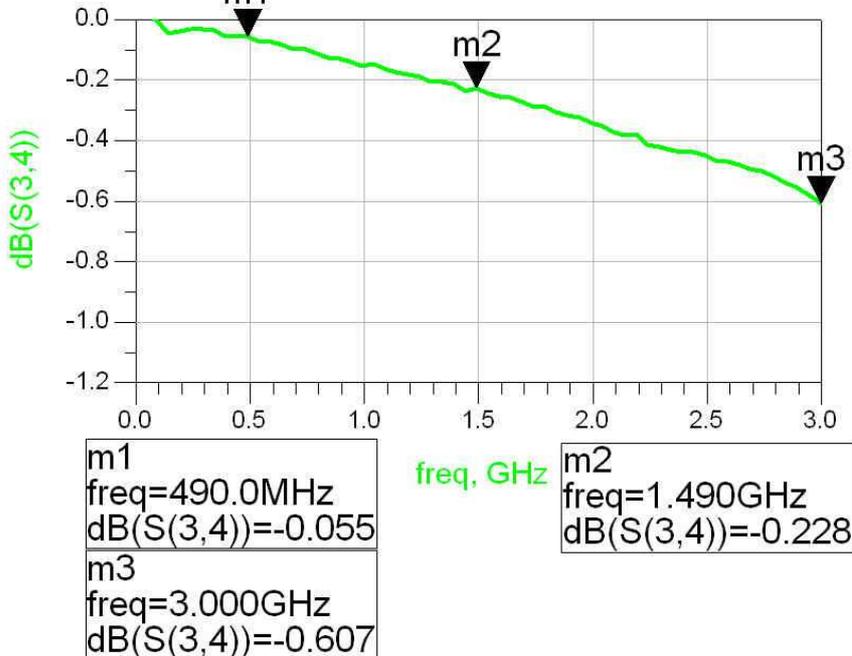
Series : TNC

Insertion loss direct line



the measurement includes the insertion loss due to the test board and connectors

Insertion loss switched line



the measurement includes the insertion loss due to the test board and connectors

Issue : 0823 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



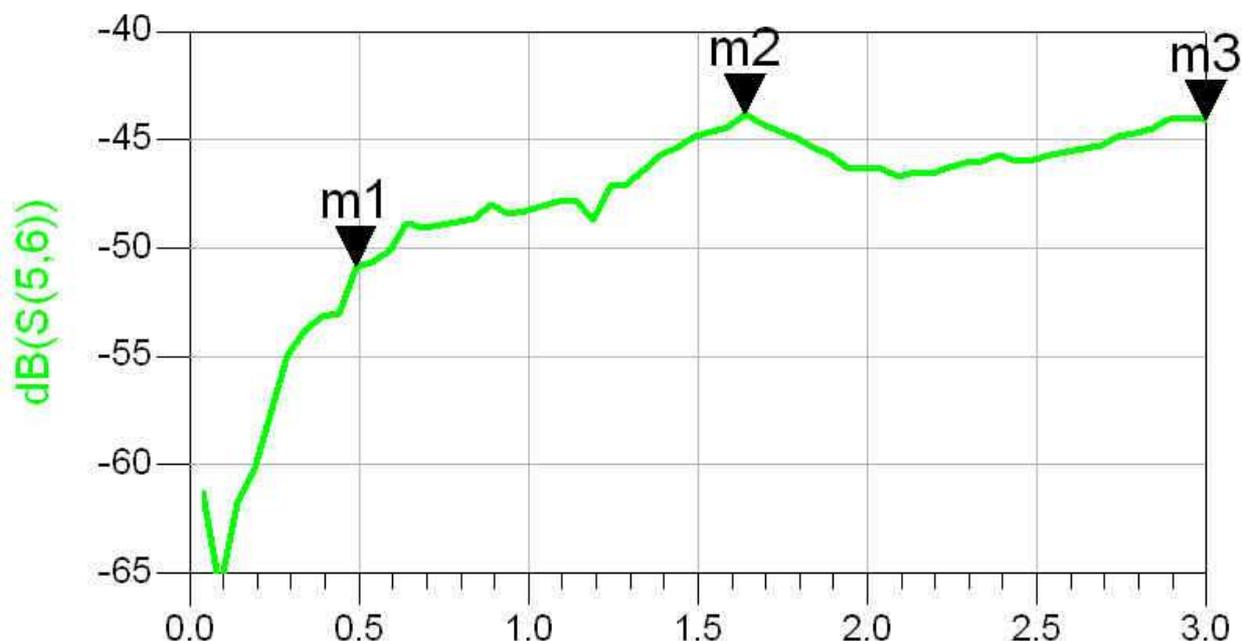
TNC SWITCH-EDGE CARD-SMT LEFT TYPE

**R143.422.947**

PACKAGING IN REEL 110

Series : TNC

Isolation switched line



m1  
freq=490.0MHz  
dB(S(5,6))=-50.856

freq, GHz

m2  
freq=1.640GHz  
dB(S(5,6))=-43.790

m3  
freq=3.000GHz  
dB(S(5,6))=-44.091

Issue : 0823 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



**TNC SWITCH-EDGE CARD-SMT LEFT TYPE**

**R143.422.947**

**PACKAGING IN REEL 110**

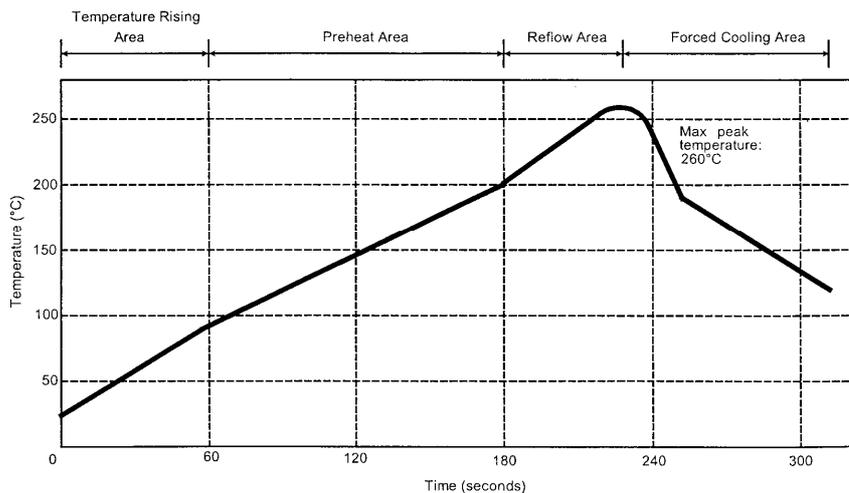
Series : TNC

**SOLDER PROCEDURE**

1. Deposit solder paste ‘Sn Ag4 Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux.  
We advise a thickness of 150 microm ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .
5. Verification of solder joints and position of the component by visual inspection.

**NOTE** : The receptacle and the plug must not be mated before completion of this procedure

**TEMPERATURE PROFILE**



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue : 0823 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

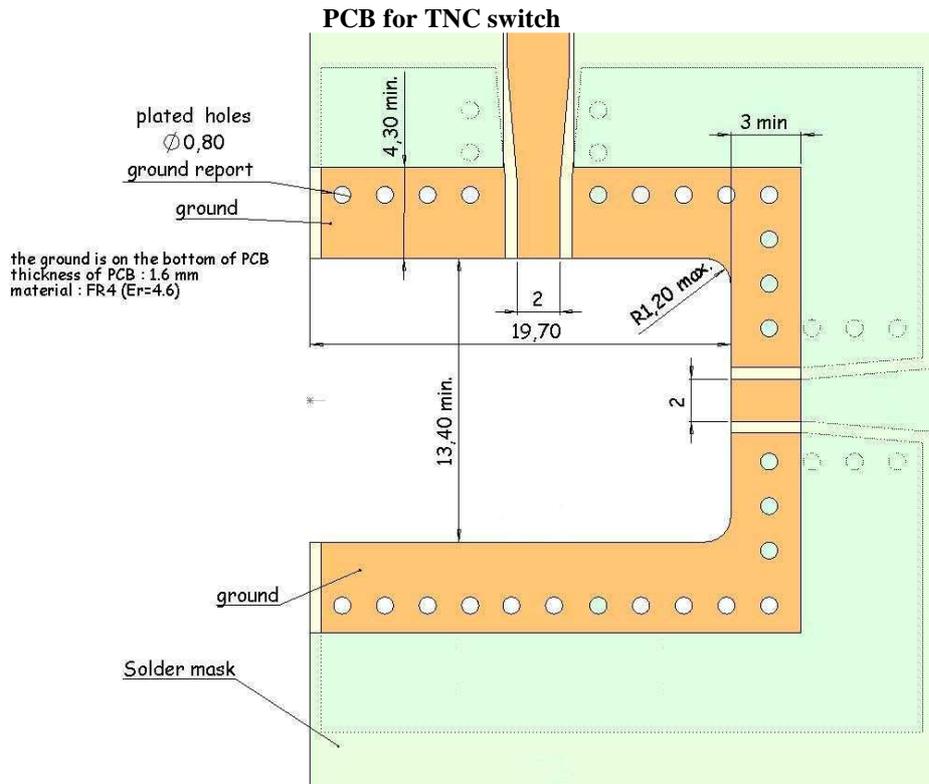


TNC SWITCH-EDGE CARD-SMT LEFT TYPE

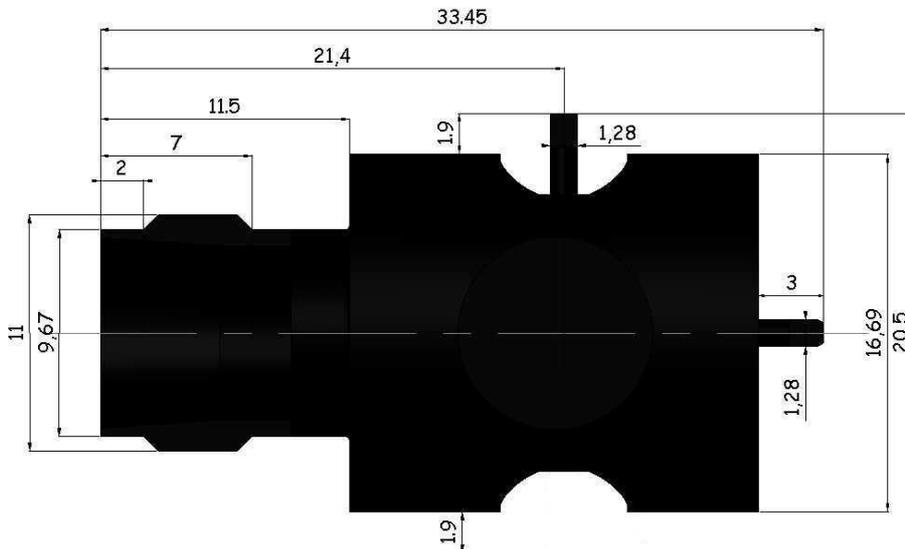
**R143.422.947**

PACKAGING IN REEL 110

Series : TNC



Shadow of TNC switch for video camera



Issue : 0823 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

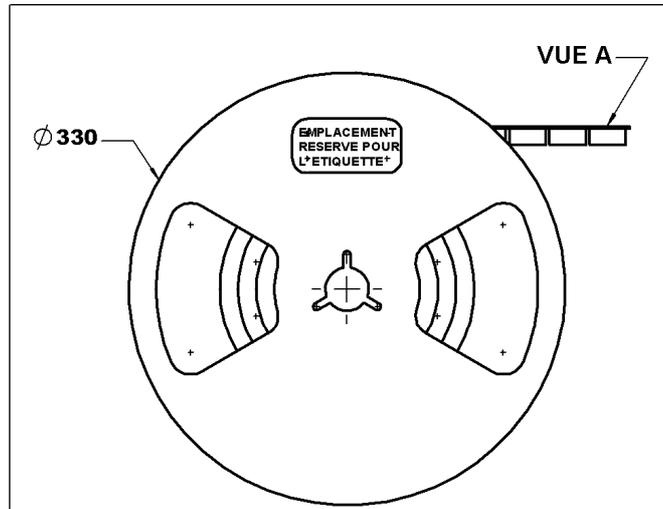


**TNC SWITCH-EDGE CARD-SMT LEFT TYPE**

**R143.422.947**

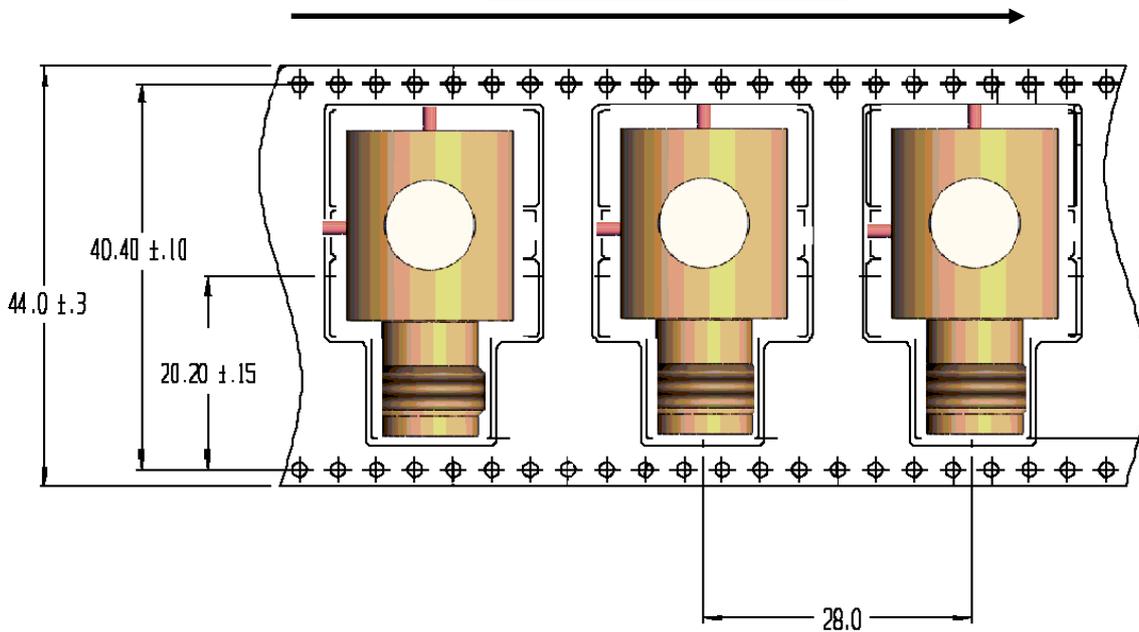
**PACKAGING IN REEL 110**

Series : TNC



bobine Ech :0.7

TAPE FEED DIRECTION



Issue : 0823 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



## Данный компонент на территории Российской Федерации

### Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9